

Atty. Docket No. CPAC.1013-1 (formerly 60084-301301)  
Appl. No. 09/893,356

PATENT

**Attachment under Rule 1.121  
(Claims)**

Claims are amended as follows:

1. (Amended) A semiconductor device package comprising:  
a semiconductor device affixed to an upper surface of a substrate, the semiconductor device having an upper surface;  
a mold cap covering at least the upper surface of the semiconductor device, the mold cap having an upper surface;  
a heat spreader affixed to at least a portion of the upper surface of the mold cap, the heat spreader being entirely external to the mold cap.
2. (Unchanged)
3. (Amended) The package of claim 1 wherein a portion of the heat spreader [lying] overlying the semiconductor device protrudes downward toward the upper surface of the semiconductor device, and a corresponding portion of the mold cap is thinner between the upper surface of the semiconductor device and the heat spreader than more peripherally.
4. (Unchanged)
5. (Unchanged)
6. (Unchanged)
7. (Unchanged)
8. (Unchanged)
9. (Unchanged)

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The following claim is new.

10. (New) The package of claim 1 wherein the heat spreader is entirely free of direct contact with the substrate.